

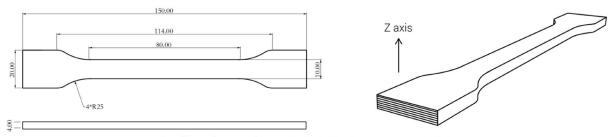
DREMC PC ABS is modified PC optimised with mixture of PC and ABS materials to improve the heat resistances and printability compared to PC. Cost effective and ideal filament for functional prototypes and small production run for automotive parts and applications.

Physical Properties

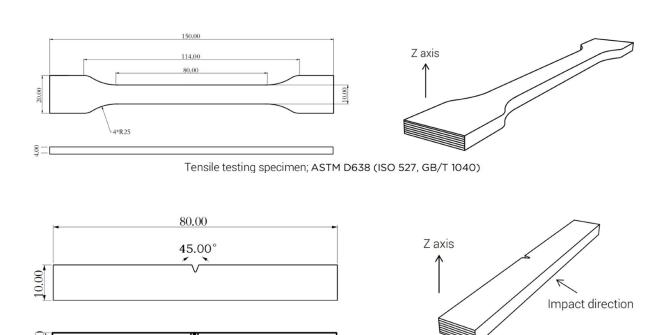
| | Testing Method | Typical value |
|---------------------|--------------------|---------------|
| Density | ISO 1183, GB/T1003 | 1.14 g/cm3 |
| Melt index | 250°C/2.15Kg | 20 g/10min |
| Moisture Absorption | ISO 62 | 1 % |
| HDT | ISO 75 / 0.455 MPa | 118°C |
| Continuous Use | IEC 60216 | 120°C |

Mechanical Properties

| | Testing Method | Typical value |
|---------------------|----------------|----------------------|
| Tensile strength | ISO 527 | 44 Mpa |
| Elongation at break | ISO 527 | 25 % |
| Flexural Modulus | ISO 527 | 800 Mpa |
| Flexural Strength | ISO 178 | 72 Mpa |
| Impact Strength | ISO 180 | 44 Kj/m ² |



Tensile testing specimen; ASTM D638 (ISO 527, GB/T 1040)



Impact testing specimen; ASTM D256 (ISO 179, GB/T 1043)

Testing Sample Conditions:

Nozzle Diameter 0.4mm

Nozzle Temperature: 265 °C

Printing Speed: 30-50mm/s

Layer: 0.12mm

Infill: 100%

DISCLAIMER:

The typical values presented in this data sheet are intended for reference and comparison purposes only. They should not be used for design specifications or quality control purposes. Actual values may vary significantly with printing conditions. End- use performance of printed parts depends not only on materials, but also on part design, environmental conditions, printing conditions, etc. Product specifications are subject to change without notice.

Each user is responsible for determining the safety, lawfulness, technical suitability, and disposal/recycling practices of DREMC materials for the intended application. DREMC makes no warranty of any kind, unless announced separately, to the fitness for any use or application. DREMC shall not be made liable for any damage, injury or loss induced from the use of DREMC materials in any application.